

Claim 9 (amended).

Electrically conductive, thermoplastic and heat-

activatable adhesive film, comprising

- i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,
- ii) a) one or more tackifying resins in a proportion of from 5 to 50% by weight or
 - b) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, or
 - c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,
- and
- iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,
- iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film.

Claim 10 (Twice Amended). Adhesive film according to Claim 9, wherein

the thermoplastic polymer comprises a member selected from the group consisting of thermoplastic polyolefins, polyesters, polyurethanes or polyamides and modified rubbers.

Claim 15 (Amended). A method for implanting electrical modules in a card

body provided with a cutout for accommodating an electronic module which on